

IMPLANTABLE MEDICAL DEVICE FOR MINIMALLY-INVASIVE INSERTION

Cross-Reference to Related Applications

The present application claims priority to and the benefit of U.S. Provisional Patent Application No. 61/745,086, filed December 21, 2012, which is hereby incorporated by reference in its entirety.

Field of the Disclosure

The present disclosure relates generally to multi-reservoir containment devices, including but not limited to medical devices, such as implantable medical devices, having containment reservoirs for confining substance or subcomponents for precisely controlled exposure or release. In certain aspects, the present disclosure relates to improved designs of such devices configured for insertion into a patient via minimally invasive instruments, such as trocars, catheters, injectors, and the like.

Background

Typical implantable medical devices, such as pacemakers and implantable cardioverter defibrillators, are designed with two or more housing components or shells that contain the control electronics, power source, and other device specific components. A header is also used to provide electrical connections into and out of the device. The housing and header (or feedthrough) are designed to be hermetic to prevent liquid or gas exchange between the internal components (which are typically not biocompatible) and body fluids. It is noted, however, that certain implants with epoxy based headers do not achieve long term hermeticity. Design and manufacturing methods of implantable devices have evolved with the goal of ensuring hermeticity.

MicroCHIPS Inc. designs and manufactures implantable devices based on microchips that include reservoir arrays containing biosensors or drugs, for example. **FIG. 1** shows a possible conventional approach for assembly of components in an implantable medical device **10**, which includes a microchip assembly **12**. The microchip assembly **12**, which is also referred to as a microchip element, includes microreservoirs, each of which may contain a drug for controlled delivery *in vivo* or a sensor for controlled exposure *in vivo*. The microchip

assembly **12** is attached to a feedthrough **16** that is welded to the housing **14**. Such microchip assemblies or elements are described, for example, in U.S. Patent 7,510,551 to Uhland *et al.* and U.S. Patent 7,604,628 to Santini Jr. *et al.* The feedthrough **16** contains electrically conductive pins that are metallurgically brazed to metallized surfaces on and through an alumina disc. A typical pin count exceeds 100, and in more complex designs, can be over 400. The consequence of such designs is that each pin connection potentially can be a leak point.

In addition, each feedthrough pin is electrically connected to an electronic component inside the housing. Some designs utilize a wire from the pin to the circuit, while the illustrated design attaches the feedthrough **16** directly to a conventional plastic circuit board **18** (which generally would be unsuitable for continuous in vivo contact with the patient). These electrical connections require testing to ensure continuity. As a result, the pin count impacts the cost of the feedthrough, and that cost increases as the number of feedthrough pins increases in the implantable device. Consequently, due to this complex design requirement, the resulting manufacturing, and the required acceptance tests, the feedthrough is a relatively expensive component.

Another disadvantage of conventional implantable device designs based on a feedthrough or header attached to housing components is that the overall volume of the resulting device is larger than ideally desired, because several discrete components make up the assembly.

Furthermore, electronic-based implantable devices that use radio frequency to wirelessly transfer information in and out of the body require an antenna. Radio frequency waves are significantly attenuated when the antenna is placed in a conventional metallic housing, and therefore, the antenna typically is placed on the surface of the housing, utilizing the existing feedthrough or another feedthrough dedicated for this application.

It therefore would be desirable to eliminate or mitigate any or all of the foregoing disadvantages associated with conventional designs of implantable medical devices. In one particular need, it would be desirable to provide improved housing hermeticity (*e.g.*, fewer potential leak paths), simpler construction, and a smaller overall device volume.

In conjunction with the desire to provide improved hermetic reservoir devices, it would also be advantageous to improve the manner in which such actively-controlled reservoir devices can be operably deployed into a patient in need thereof. For example, it would be desirable to reduce the size of incisions and/or increase the possible range of tissue sites into which the device can be suitably deployed without undue pain or discomfort to the patient. It would be desirable to provide device configurations conducive to such uses in patients.

Summary

Some or all of the above needs and/or problems may be addressed by one or more embodiments described herein. In one embodiment, a containment device is provided that includes an elongated microchip element having one or more containment reservoirs that are configured to be electrically activated to open. The containment device also includes an elongated electronic printed circuit board (PCB) comprising a biocompatible substrate. The elongated PCB also comprises a first side on which one or more electronic components are fixed and an opposed second side on which the elongated microchip element is fixed in electrical connection to the one or more electronic components. Further, the containment device includes an elongated housing fixed to the elongated PCB. The elongated housing is configured to hermetically seal the one or more electronic components of the elongated PCB within the elongated housing.

According to a first aspect of the present invention, there is provided a containment device, comprising: an elongated microchip element comprising one or more containment reservoirs that are configured to be electrically activated to open; an elongated electronic printed circuit board (PCB), wherein the elongated PCB comprises a first side on which one or more electronic components are fixed and an opposed second side on which the elongated microchip element is fixed in electrical connection to the one or more electronic components; and an elongated housing fixed to the elongated PCB, wherein the elongated housing is configured to surround the first side of the elongated PCB such that the elongated housing and the elongated PCB collectively form a hermetic enclosure around the one or more electronic components to hermetically seal the one or more electronic components of the elongated PCB within the elongated housing.

According to a second aspect of the present invention, there is provided a containment device, comprising: a microchip element comprising one or more containment reservoirs that are configured to be electrically activated to open; an electronic printed

circuit board (PCB) comprising a biocompatible substrate, wherein the PCB comprises a first side on which one or more electronic components are fixed and an opposed second side on which the microchip element is fixed in electrical connection to the one or more electronic components; and a housing fixed to the PCB, wherein the housing is configured to surround the first side of the PCB such that the housing and the PCB collectively form a hermetic enclosure around the one or more electronic components to hermetically seal the one or more electronic components of the PCB within the housing, wherein the containment device comprises an elongated tubular structure configured to be injected in a human or animal subject via a medical instrument.

According to a third aspect of the present invention, there is provided a method of assembling a containment device, comprising: providing an elongated microchip element comprising one or more containment reservoirs that are configured to be electrically activated to open; fixing the elongated microchip element to a first side of an elongated electronic printed circuit board (PCB) which comprises a biocompatible substrate; electrically connecting the elongated microchip element to one or more electronic components which are fixed on a second side of the elongated PCB; and hermetically sealing the one or more electronic components of the elongated PCB within an elongated housing that is fixed to the elongated PCB by surrounding the first side of the elongated PCB such that the elongated housing and the elongated PCB collectively form a hermetic enclosure around the one or more electronic components.

Other embodiments, aspects, and features of the containment device will become apparent to those skilled in the art from the following detailed description, the accompanying drawings, and the appended claims.

Brief Description of the Drawings

Reference will now be made to the accompanying drawings, which are not necessarily drawn to scale.

FIG. 1 schematically depicts an exploded perspective view of a prior art containment device including a microchip assembly.

FIG. 2A schematically depicts a cross-sectional view of an assembled containment device including a microchip assembly according to an embodiment.

FIG. 2B schematically depicts an exploded cross-sectional view of the containment device shown in **FIG. 2A**.

FIG. 2C schematically depicts a top view of the containment device shown in **FIGS. 2A** and **2B**.

5 **FIG. 3** schematically depicts a perspective view of the containment device illustrated
in **FIGS. 2A-2C**.

FIG. 4 schematically depicts a close-up, cross-sectional view of a portion of a containment device according to an embodiment.

FIG. 5A schematically depicts a cross-sectional view of a microchip element assembly according to an embodiment.

FIG. 5B schematically depicts an exploded cross-sectional view of the microchip element assembly shown in **FIG. 5A**.

FIG. 6 schematically depicts a cross-sectional close-up view of a portion of an assembled containment device including a microchip assembly according to an embodiment.

15 **DETAILED DESCRIPTION**

Illustrative embodiments will now be described more fully hereinafter with reference to the accompanying drawings, in which some, but not all embodiments are shown. The representative embodiments described in the disclosure may be embodied in many different forms and should not be construed as limited to the embodiments set forth herein. Like numbers refer to like elements throughout.

The containment devices and assemblies described herein provide, among other advantages, significantly improved space efficiency of the assembled devices. For example, compared with prior art devices, embodiments of the present devices can hold the same or a larger drug payload in the same or a smaller overall device volume. Moreover, in certain embodiments, the devices and methods advantageously eliminate the need for a costly and complex feedthrough, provide a thinner, sleek implant due to the elimination of the feedthrough, provide improved reliability by eliminating numerous feedthrough pins and electrical connections, provide improved reliability by reducing the number of hermetic interfaces, simplify tests to confirm functionality, and provide a simpler assembly. This can be particularly important in embodiments in which the containment device is an implantable

medical device intended for long-term implantation in a human or animal subject via minimally-invasive insertion means, such as through a small incision, trocar, cannula, injector, or similar like medical instrument.

The containment devices provided herein may be further understood with reference to the following exemplary embodiments, including the containment device **110** illustrated in **FIGS. 2A-3**. The containment device **110** includes an elongated microchip element **112** which comprises one or more containment reservoirs **114** that can be electrically activated to open. The containment device **110** also includes an elongated electronic printed circuit board (PCB) **116**. The elongated PCB **116** comprises a biocompatible substrate and has a first side **118** on which one or more electronic components **120** are fixed and an opposed second side **122** on which the microchip element **112** is fixed in electrical connection to the one or more electronic components **120**. As will be explained below with reference to **FIG. 4**, the electronic components **120** on the first side **118** of the PCB **116** are in electrical (*i.e.*, operable) communication with the microchip element **112**.

It is understood that the containment device **110** may include any suitable number of microchip elements **112** (*e.g.*, from 1 to 6) and that each microchip element **112** may include a plurality of discrete containment reservoirs **114** (*e.g.*, from 10 to 750 reservoirs). More microchip elements **112**, and fewer or more containment reservoirs **114**, per containment device **110** are also envisioned. Moreover, it is understood that the containment device **110** may include any suitable number of PCBs **116**.

As shown in **FIGS. 2A-2C**, embodiments particularly suitable for minimally invasive insertion into a patient may have long, narrow microchip elements **112** with elongated arrays of closely spaced containment reservoirs. **FIG. 2C** shows a 2 x 28 reservoirs array. In one embodiment, the elongated array has from 1 to 4 rows of 20 to 40 reservoirs. In other embodiments, other numbers of rows and reservoirs are envisioned.

The “electronic printed circuit board” (PCB) refers to a substrate that mechanically supports and electrically connects electronic components using conductive pathways, tracks, or signal traces as known in the art. In embodiments, the PCB includes a biocompatible and hermetic substrate material. Suitable such materials include ceramics, such as alumina and silicon nitride. Multi-layer alumina PCBs have been successfully designed and manufactured.

See, for example, U.S. Patent Application Publication No. 2003/0034564. These laminations may be the result of combining conductive layers, dielectric layers, and aluminum oxide (Al_2O_3 , alumina) in a low temperature co-fired process. The alumina is referred to as low temperature co-fired ceramic (LTCC). These biocompatible ceramics also function as a hermetic barrier, eliminating the need, in some instances, for conventional metallic housing elements. Other materials or combinations of materials capable of performing all or some of the described function may also be used.

The term “biocompatible” as used herein generally refers to materials of construction that are suitable for long-term or short-term implantation into a human or animal subject, *e.g.*, a patient. Such materials of constructions are known in the art of implantable medical devices.

As used herein, the term “hermetic seal” refers to preventing undesirable ingress or egress of chemicals (*e.g.*, water vapor, water, oxygen, etc.) into or from one or more compartments of the device, such as the device reservoirs or housings, over the useful life of the device. For purposes herein, a material/seal that transmits helium (He) at a rate less than 1×10^{-9} atm*cc/sec is termed hermetic.

The containment device **110** may include an elongated housing **124**. The elongated housing **124** is configured to hermetically seal the one or more electronic components **120** of the elongated PCB **116** within the elongated housing **124**. That is, the elongated housing **124** is configured to surround the first side **118** of the elongated PCB **116**. In this manner, the elongated housing **124** and the elongated PCB **116** collectively form a hermetic enclosure around the one or more electronic components **120**. Desirably, the elongated housing **124** and at least a portion of the outward facing second side **122** of the elongated PCB **114** are formed of a biocompatible material. For example, in some instances, the elongated housing **124** may be made of a biocompatible metal or alloy, such as titanium or stainless steel. In other instances, the elongated housing **124** may be made of a biocompatible polymer. In certain embodiments, at least a portion of the elongated housing **124** has a generally cylindrical body. In some instances, the elongated housing **124** includes atraumatic surfaces. Moreover, a distal end **136** of the elongated housing **124** may be rounded.

The elongated housing **124** may comprise a battery chamber **126** configured to house one or more batteries **128** therein. Any power source or power system may be housed within the battery chamber **126**. In some instances, the battery chamber **126** may be a separate area within the elongated housing **124**. In other instances, the battery chamber **126** may be part of
5 a single enclosure formed by the elongated housing **124**. In one embodiment, the battery chamber **126** may be positioned about a proximal end **130** of the elongated housing **124**. However, the battery chamber **126** may be located at any position within the elongated housing **124**. Moreover, in some instances, the battery chamber **126** may be omitted. For example, the device power may be provided by inductive charging.

10 In certain embodiments, the battery chamber **126** may include a cover **132**. The cover **132** may be removable or permanent. The cover **132** may be configured to provide access to the batteries **128** and/or hermetically seal the one or more batteries **128** within the battery chamber **126**. That is, in a preferred embodiment, the cover **132** and the elongated housing **124** form a hermetic seal when affixed to each other. In one example, the cover **132** may be
15 located about the proximal end **130** of the elongated housing **124**.

The interface of the elongated housing **124** with the elongated PCB **116**, in a preferred embodiment, forms a hermetic seal to isolate the one or more electronic components **120** within the elongated housing **124**. In some instances, the elongated housing **124** may be welded to the elongated PCB **116**. In other instances, a biocompatible substance **134**, such as
20 a biocompatible epoxy coating (e.g., an epoxy resin) or other biocompatible coating material, may be disposed over at least a portion of the elongated microchip element **112**, the elongated PCB **116**, and the elongated housing **124**. This coating may be multilayered, and it may include a hermetic material so long the material does not interfere with the operation of any of the components, such as the electronic components **120** or the batteries **128**.

25 In certain embodiments, the containment device **110** may include a sleek, tubular profile. For example, some or all of the components associated with the containment device **110** may be elongated. That is, some or all of the components of the containment device **110**, such as the elongated microchip element **112**, the elongated PCB **116**, and the elongated housing **124**, may have a greater length than width. Furthermore, the biocompatible coating
30 substance **134**, the elongated microchip element **112**, and the elongated housing **124** may

collectively form a generally circular cross-section and rounded distal end **136** of the containment device **110**. The components may collectively fit together to form a sleek, tube-like structure or assembly that may be inserted in a human or animal subject in a minimally invasive manner. The sleek, tube-like structure or assembly preferably has atraumatic surfaces.

The biocompatible coating substance **134** may create an atraumatic surface about the containment device **110**. In certain embodiments, the surface of the containment device is formed of or coated with a lubricious substance to facilitate passage of the device to the intended tissue site.

The containment device **110** may be implanted in a human or animal subject, such as a patient in need of treatment, diagnosis, or prophylaxis, by a variety of techniques known in the art. In a preferred embodiment, the device is inserted into the patient at a subcutaneous tissue site. A variety of insertion tools and systems may be used depending on the particular size of the implant and the particular site of implantation desired for a particular medical purpose. The containment device **110** may be inserted, injected, or otherwise placed into the human or animal subject via one or a combination of minimally invasive medical instruments, including a cannula, trocar, subcutaneous insert, or a gun-like injector device or assembly. In one embodiment, a small (*e.g.*, few millimeters) incision is made in the patient's skin, and the containment device **110** is passed through the incision and into the patient just under the skin using a long, narrow inserter tool that can grasp an end of the containment device **110** in a linear low profile arrangement. The containment device **110** would be released from the inserter tool, the end of the inserter tool would be removed from the incision, and then the incision would be closed, for example with one or a few stitches. In some instances, one or more suture loops may be provided with the housing **124** and/or the cap **132**. The suture loops may be configured to anchor the containment device **110** in a subcutaneous space.

The electronic components **120** provide any of a number of functions for the containment device **110**. Examples include, but are not limited to, a controller (*e.g.*, one or more microprocessors) and power source (*e.g.*, a battery or capacitor) for electrically activating the reservoir **114** to cause it to become opened and/to communicate with a sensor, for example, located within the reservoir **114** or with another device remotely located from

the containment device **110**. Other electronic components may include, for example, telemetry hardware, capacitors, transistors, and diodes, as well as the control means for actuating the reservoir caps. The control means may include an input source, a microprocessor, a timer, a demultiplexer (or multiplexer). In an embodiment, the electronic components include components for wirelessly receiving energy for charging an on-board storage capacitor, which may further reduce the space requirements for the electronic components on-board the containment device **110**. In some instances, the electronic components may include an antenna, such as a transmitter, receiver, or transceiver.

The containment reservoir **114** of the microchip element **112** may be configured to open/activate in a variety of ways, which may be known in the art. In one embodiment, the containment reservoir **114** is structured and configured to be electrically activated to open as described in U.S. Patent No. 7, 510,551 and U.S. Patent No. 7,604,628, which are incorporated herein by reference.

One embodiment of the electrical connection between a PCB/electronic components and a microchip element is illustrated in **FIG. 4**. The figure shows part of the microchip element **312** including two containment reservoirs **344**. Each containment reservoir **344** has an opening that is (initially) closed off by a reservoir cap **348**. The containment reservoir **344**, which is formed at least in part in a substrate **343**, has a closed end opposed to the opening and a sidewall therebetween. The microchip element **312** is secured to a side of a PCB **314**, and electronic component **318** is secured on the opposed side of the PCB **314**. The PCB **314** includes a via **330** which electrically connects electronic component **318** to the microchip element **312**. Via **330** is mechanically and electrically connected to metallized conductive surfaces **332A**, **332B** on the PCB **314**, and the microchip element **312** is wirebonded **334** to the metallized conductive surface **332A**. Any via or wirebond combination may be used. A biocompatible coating substance **336** is applied over the wire bond to secure and protect the connection, and typically will coat part of the surface of the PCB **314**, part of the microchip element **312**, and part of the housing **320** but not the reservoir caps **348**. The coating substance **336** may be a polymer, such as an epoxy or other resin. Any suitable coating may be used.

In one embodiment, the reservoir caps **348** are structured and configured to be electrically activated to open as described in U.S. Patent No. 7, 510,551 and U.S. Patent No. 7,604,628, which are incorporated herein by reference. That is, in a preferred embodiment, the reservoirs are configured to open by being disintegrated by electrothermal ablation. The reservoir caps **348** may be formed of a metal film, which may comprise a single layer or a laminate structure. For example, the reservoir cap **348** may comprise gold, platinum, titanium, or a combination thereof. In other embodiments, the reservoir cap **348** can be configured to be activated or opened by a mechanical or electrochemical mechanism.

The containment reservoir of the microchip element may be a “microreservoir” which generally refers to a reservoir having a volume equal to or less than 500 μL (e.g., less than 250 μL , less than 100 μL , less than 50 μL , less than 25 μL , less than 10 μL , etc.). In another embodiment, the containment reservoirs may be a “macroreservoir” which generally refers to a reservoir having a volume greater than 500 μL (e.g., greater than 600 μL , greater than 750 μL , greater than 900 μL , greater than 1 mL, etc.) and less than 5 mL (e.g., less than 4 mL, less than 3 mL, less than 2 mL, less than 1 mL, etc.). The terms “reservoir” and “containment reservoir” are intended to encompass both microreservoirs and macroreservoirs unless explicitly indicated to be limited to one or the other.

In another aspect, improved microchip elements and methods for their manufacture are provided. In a preferred embodiment, the microchip device element includes a relatively thin silicon substrate bonded to a relatively thicker primary substrate formed of a polymer or a glass or other ceramic material. Advantageously, by defining the reservoirs in the primary substrate rather than the silicon substrate, the reservoirs may be formed using processes other than dry reactive ion etching (DRIE). This is important, not just because DRIE processes are expensive, but also because under the conventional process, the DRIE processes occurred after deposition of the reservoir cap film, unnecessarily exposing the reservoir cap film to subsequent processing, which can negatively impact the yield of acceptable (e.g., hermetic) reservoir caps.

In addition, by adding the positive sealing features (e.g., gold sealing rings) to the silicon substrate, this keeps all of the high tolerance microfeatures to only the silicon substrate, which in turn advantageously frees up the primary substrate to be made by other,

potentially lower tolerance, manufacturing processes. In this way, the reservoir can be made much deeper and thereby increase the unit reservoir payload. In one embodiment, the primary substrate is made by a casting or molding process using ceramic or polymeric materials that allows for formation of reservoirs that are deeper than conventional reservoirs and have smoother side walls than would be readily possible using DRIE. This cast or molded substrate then may be gold plated in and about sealing grooves formed therein for bonding with the positive sealing features on the silicon substrate.

An exemplary embodiment of the elongated microchip element is illustrated in **FIG. 5A** and **FIG. 5B**. The elongated microchip element **412** includes a primary substrate **440** and a silicon substrate **442**, which are bonded together. The silicon substrate **442** has a first side, an opposed second side, and apertures **446** extending therethrough. Three apertures **446** are shown for each reservoir **444**. The first side of the silicon substrate **442** includes reservoir caps **448** which close off the apertures **446** until the reservoir needs to be opened. In a preferred embodiment, the reservoir caps **448** are electrically conductive. For example, the reservoir caps **448** may be in the form of a metal film. The silicon substrate **442**, apertures **446**, and reservoir caps **448** can be made using microfabrication techniques known in the art. For example, the photolithography, etching, and deposition techniques described in U.S. Patent No. 7,604,628 may be used to form the apertures **446** in a polysilicon substrate closed off by metal reservoir caps **448**.

The primary substrate **440** includes two reservoirs **444** in this illustration, although more or less reservoirs may be included. Each reservoir **444** is defined by a closed end wall, an open end, and at least one sidewall extending between the closed end wall and the open end. As mentioned above, the primary substrate **440** may be formed of silicon. In other embodiments, the substrate may be formed of a metalloid, polymer, glass, or other ceramic material. Any suitable material may be used. The substrate and reservoirs may be made by any suitable process, including but not limited to molding, casting, micromachining, and build-up or lamination techniques known in the art. In one embodiment, the primary substrate **440** is made of/by low temperature co-fired ceramics (LTCC). It may further include a coating layer on all or a portion of the substrate, for example to provide or improve hermeticity, biocompatibility, bonding, and/or reservoir content compatibility, stability, or

release. Depending on the purpose of the coating layer, it may be applied inside the reservoirs **444**, outside of the reservoirs **444**, or both. Examples of possible coating materials include biocompatible metals, such as gold, and polymers, such as parylene.

The primary substrate **440** and the silicon substrate **442** are bonded together using any suitable method, to hermetically seal the reservoirs **444**. In this way, the open end of the reservoir **444** is in fluid communication with the apertures **446** for controlled release or exposure of reservoir contents. In a preferred embodiment, the substrates are hermetically sealed together using a compression cold welding process, such as described in U.S. Patent No. 8,191,756, which is incorporated herein by reference.

As shown in **FIGS. 5A** and **5B**, the second side of the silicon substrate **442** includes ring structures **452** formed thereon, and the first side of the primary substrate **440** includes grooves **450**. These bonding features are compressed together to form a cold weld bond hermetic seal surrounding the individual reservoirs **444**. The ring structures **452** may be formed by a depositing gold or another metal layer on the silicon substrate **442**. The grooves **450** may be etched in the silicon and then coated with a metallized layer of the same material as the metal ring. Variations of this embodiment are envisioned, for example, where other positive and negative bonding features are provided in/on either or both interfacing surfaces of the silicon substrate **442** and the primary substrate **440**.

The primary substrate **440** is generally relatively thicker than the silicon substrate **442**, and all or at least a majority (greater than 50%) of the reservoir sidewall height (or depth) is defined by the primary substrate **440**. In an embodiment, the silicon substrate **442** has thickness that is between 5% and 50% of the thickness of the primary substrate **440** at the bonded interfaces of the substrates.

Although not shown in the **FIG. 4** or **FIG. 5A**, the reservoirs **344** and **444**, respectively, include reservoir contents positioned therewithin. The reservoirs can be configured to store essentially any substance or device component in need hermetic containment and subsequent release or exposure at a selected time. The reservoir content may be, for example, a chemical reagent, a drug formulation, or sensor or component thereof, such as an electrode. In an embodiment, a single device includes at least one containment reservoir containing a biosensor and at least one reservoir containing a drug formulation. Examples of

various reservoir contents are described for example in U.S. Patent No. 7,510,551; U.S. Patent No. 7,497,855; U.S. Patent No. 7,604,628; U.S. Patent No. 7,488,316; and PCT WO 2012/027137.

An exemplary embodiment of a containment device **600** including a microchip element **612** is illustrated in **FIG. 6**. The containment device **600** includes a ceramic PCB **614** which has via **630** electrically connecting electronic component **618** to the microchip element **612**. The electronic component **618** is secured on a first side of the ceramic PCB **614**, and the microchip element **612** is secured on the opposing second side of the PCB **614**. The via **630** electrically connects to a metallized conductive surface **632** on the first side of the PCB **614**. The electrical circuitry **635** of the microchip element **612** is electrically connected to the metallized surface **632** by a wirebond **634**. An epoxy **633** coats the wirebond **634** and at least a portion of the microchip element **612**, the ceramic PCB **614**, and a housing **620**. In this manner, the epoxy **633** ensures that the containment device **600** is void of any atraumatic surfaces. The epoxy **633** also may passivate the wirebond **634**. The second side of the ceramic PCB **614** also includes a metallized conductive surface **637**, which is electrically connected to the electronic component **618**. Although not shown in this illustration, the containment device **600** may include multiple microchip elements, as well as multiple vias, electronic components, and wirebonds. Moreover, the containment device **600** (with the exception of the reservoir caps) may be completely or partially coated by the epoxy **633**.

The microchip element **612** includes a primary substrate **640** and a silicon substrate **642**. The primary substrate **640** and silicon substrate **642** are bonded together by compression cold welding at/adjacent the interface of a ring structure and groove structure tongue **650/652**. Reservoirs **644** are defined in the primary substrate **640** with the open end in fluid communication with apertures **646** defined through the silicon substrate **612**. Electrically conductive reservoir caps **648** sealingly cover the apertures **646** and reservoirs **644**.

Modifications and variations of the methods and devices described herein will be obvious to those skilled in the art from the foregoing detailed description. Such modifications and variations are intended to come within the scope of the appended claims.

I claim:

1. A containment device, comprising:
 - an elongated microchip element comprising one or more containment reservoirs that are configured to be electrically activated to open;
 - an elongated electronic printed circuit board (PCB), wherein the elongated PCB comprises a first side on which one or more electronic components are fixed and an opposed second side on which the elongated microchip element is fixed in electrical connection to the one or more electronic components; and
 - an elongated housing fixed to the elongated PCB, wherein the elongated housing is configured to hermetically seal the one or more electronic components of the elongated PCB within the elongated housing.
2. The containment device of claim 1, wherein at least a portion of the elongated housing comprises a generally cylindrical body.
3. The containment device of claim 1, wherein the elongated housing comprises a battery chamber configured to house one or more batteries therein.
4. The containment device of claim 3, wherein the battery chamber comprise a cover configured to hermetically seal the one or more batteries within the battery chamber.
5. The containment device of claim 1, wherein the elongated housing is formed of a biocompatible metal, alloy, or polymer.
6. The containment device of claim 1, wherein the elongated PCB comprises a biocompatible substrate.
7. The containment device of claim 6, wherein the biocompatible substrate comprises glass, alumina, or another ceramic.

8. The containment device of claim 1, wherein the elongated PCB comprises at least one via configured to electrically connect at least one of the one or more electronic components to the elongated microchip element.
9. The containment device of claim 8, wherein the at least one via is electrically connected to a metallized conductive surface on the second side of the elongated PCB, and wherein the metallized conductive surface is wirebonded to the elongated microchip element.
10. The containment device of claim 9, wherein a biocompatible coating substance is positioned over the wire bond to secure and protect the connection and create an atraumatic surface about the containment device.
11. The containment device of claim 10, wherein the biocompatible coating substance, the elongated microchip element, and the elongated housing collectively form a generally circular cross-section and rounded distal end of the containment device.
12. The containment device of claim 1, wherein the one or more containment reservoirs comprise microreservoirs containing a drug formulation or a sensor element.
13. The containment device of claim 1, wherein the elongated microchip element comprises:

a silicon substrate having a first side, an opposed second side, and at least one aperture extending therethrough, wherein the first side of the silicon substrate comprises an electrically conductive reservoir cap which closes off the at least one aperture;

a primary substrate which is formed of silicon or other metalloid, a polymer, or a glass or other ceramic material, wherein the primary substrate has at least one of the one or more reservoirs which is defined by a closed end wall, an open end, and at least one sidewall extending between the closed end wall and the open end; and

reservoir contents positioned within the at least one reservoir,

wherein the second side of the silicon substrate is hermetically bonded to the primary substrate such that the open end of the reservoir is in fluid communication with the at least one aperture for controlled release or exposure of reservoir contents.

14. The containment device of claim 13, wherein the silicon substrate has a thickness that is between 5% and 50% of the thickness of the primary substrate at the bonded interfaces of the substrates.
15. The containment device of claim 13, wherein the primary substrate comprises a metal coating over at least a part of the polymer, glass or other ceramic material of the primary substrate.
16. The containment device of claim 15, wherein the metal coating coats the at least one sidewall and/or the closed end wall of the at least one reservoir.
17. The containment device of claim 13, wherein the second side of the silicon substrate comprises at least one ring structure formed thereon.
18. The containment device of claim 17, wherein the at least one ring structure comprises gold or another metal.
19. The containment device of claim 17, wherein the primary substrate comprises at least one groove structure, wherein the at least one ring structure and the at least one groove structure are configured to form a hermetic bond.
20. The containment device of claim 17, wherein the surface of the primary substrate in and/or adjacent to the at least one groove structure comprises a metal coating.
21. The containment device of claim 20, wherein the metal coating comprises gold.
22. The containment device of claim 1, wherein the elongated housing comprises titanium.

23. A containment device, comprising:
- a microchip element comprising one or more containment reservoirs that are configured to be electrically activated to open;
 - an electronic printed circuit board (PCB) comprising a biocompatible substrate, wherein the PCB comprises a first side on which one or more electronic components are fixed and an opposed second side on which the microchip element is fixed in electrical connection to the one or more electronic components; and
 - a housing fixed to the PCB, wherein the housing is configured to hermetically seal the one or more electronic components of the PCB within the housing, wherein the containment device comprises an elongated tubular structure configured to be injected in a human or animal subject via a medical instrument.
24. A method of assembling a containment device, comprising:
- providing an elongated microchip element comprising one or more containment reservoirs that are configured to be electrically activated to open;
 - fixing the elongated microchip element to a first side of an elongated electronic printed circuit board (PCB) which comprises a biocompatible substrate;
 - electrically connecting the elongated microchip element to one or more electronic components which are fixed on a second side of the elongated PCB; and
 - hermetically sealing the one or more electronic components of the elongated PCB within an elongated housing that is fixed to the elongated PCB.
25. The method of claim 24, wherein providing the elongated microchip element further comprises:
- microfabricating a silicon substrate having a first side, an opposed second side, and at least one aperture extending therethrough, wherein the first side comprises an electrically conductive reservoir cap which closes off the at least one aperture;
 - casting or molding a polymer or a glass or other ceramic material to form a primary substrate having at least one of the one or more reservoirs which is defined by a closed end wall, an open end, and at least one sidewall extending between the closed end wall and the open end;

providing reservoir contents within the at least one reservoir; and
bonding the silicon substrate to the primary substrate such that the open end of the reservoir is in fluid communication with the at least one aperture.

26. The method of claim 25, wherein the silicon substrate has a thickness that is between 5% and 50% of the thickness of the primary substrate at the bonded interfaces of the substrates.
27. The method of claim 25, wherein the microfabricating step further comprises forming at least one ring structure on the second side of the silicon substrate.
28. The method of claim 25, wherein the primary substrate comprises at least one groove structure and the step of bonding comprises compression cold welding the at least one ring structure together with the at least one groove structure.